



**PCN# 20120817000  
Die and Data Sheet Revision for DAC8562 Devices  
Change Notification / Sample Request**

**Date:** 8/24/2012  
**To:** MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services  
Phone: +1(214) 480-6037  
Fax: +1(214) 480-6659

**20120817000**

**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
DAC7562SDGST	null
DAC7562SDSCT	null
DAC7563SDGST	null
DAC7563SDSCT	null
DAC8162SDGST	null
DAC8162SDSCT	null
DAC8163SDGST	null
DAC8163SDSCT	null
DAC8562SDGST	null
DAC8562SDSCT	null
DAC8563SDGST	null
DAC8563SDSCT	null

Technical details of this Product Change follow on the next page(s).

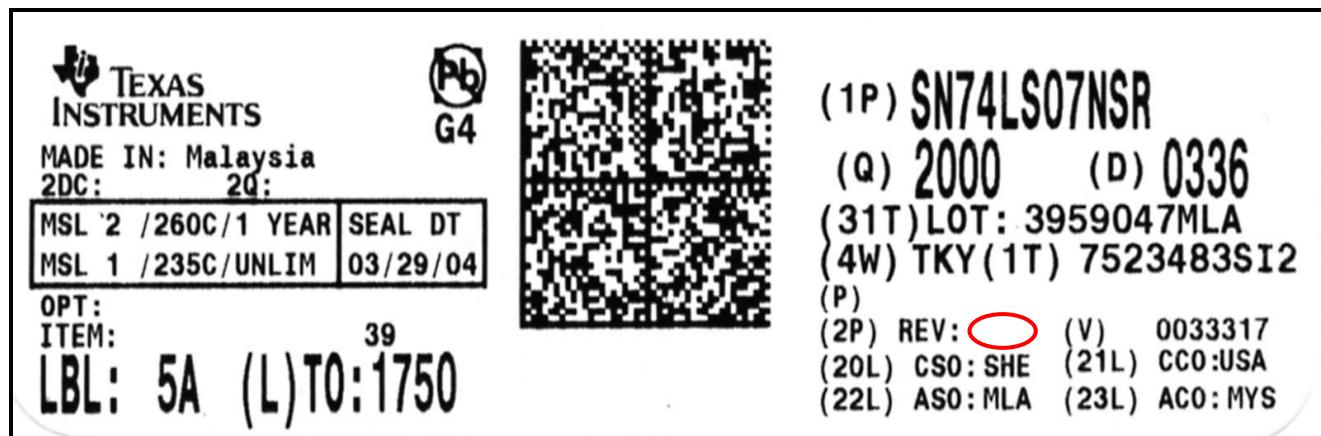
<b>PCN Number:</b>	20120817000		<b>PCN Date:</b>	08/24/2012	
<b>Title:</b>	Die and Data Sheet Revision for DAC8562 Devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Phone:</b>	+1(214)480-6037	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	11/24/2012	<b>Estimated Sample Availability:</b>			Date provided at sample request
<b>Change Type:</b>					
<input type="checkbox"/> Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials	
<input checked="" type="checkbox"/> Design	<input checked="" type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process	
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process	
<b>PCN Details</b>					
<b>Description of Change:</b>					
<p>This notification is to inform of a die and datasheet revision for DAC8562 devices. With revision C, OTP will no longer become corrupted during specific brown out events.</p>					
<b>Datasheet Revision:</b>					
<b>Device Family</b>	<b>Change From:</b>	<b>Change To:</b>			
DAC8562	SLAS719C	<a href="#">SLAS719D</a>			
<p>The updated datasheet can be accessed by the following link:  <a href="http://www.ti.com/general/docs/lit/getliterature.tsp?baseLiteratureNumber=SLAS719&amp;fileType=pdf">http://www.ti.com/general/docs/lit/getliterature.tsp?baseLiteratureNumber=SLAS719&amp;fileType=pdf</a></p>					
<b>REVISION HISTORY</b>					
<b>Changes from Revision C (June 2011, first official release) to Revision D</b>					<b>Page</b>
<ul style="list-style-type: none"> <li>• Replaced text "QFN" with "SON" (name change only, package/orderable did not change) .....</li> <li>• Typical power-down current consumption changed from 10 nA to 550 nA. ....</li> <li>• Changed power requirements specifications .....</li> <li>• Power-down current vs Temperature typical characteristic plot updated, AV<sub>DD</sub> = 5.5 V .....</li> <li>• Power-down current vs Power-supply voltage typical characteristic plot updated .....</li> <li>• Power-down current vs Temperature typical characteristic plot updated, AV<sub>DD</sub> = 2.7 V .....</li> <li>• Added Power-On Reset (POR) Levels section .....</li> </ul>					1 1 5 15 15 23 30
<b>Reason for Change:</b>					
To improve device performance and prevent brown out events.					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None.					

**Changes to product identification resulting from this PCN:**

**Die Rev designator will change as shown in table & sample label below:**

Current	New
Die Rev [2P]	Die Rev [2P]
B	C

Sample product shipping label to indicate die rev location (**not actual product label**)



**Product Affected:**

DAC7562SDGSR	DAC7563SDSCR	DAC8163SDGSR	DAC8562SDSCR
DAC7562SDGST	DAC7563SDSCT	DAC8163SDGST	DAC8562SDSCT
DAC7562SDSCR	DAC8162SDGSR	DAC8163SDSCR	DAC8563SDGSR
DAC7562SDSCT	DAC8162SDGST	DAC8163SDSCT	DAC8563SDGST
DAC7563SDGSR	DAC8162SDSCR	DAC8562SDGSR	DAC8563SDSCR
DAC7563SDGST	DAC8162SDSCT	DAC8562SDGST	DAC8563SDSCT

**Qualification Data: Approved 08/10/2012**

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

**Qual Vehicle: DAC8562SDGSR**

**Die Construction Details**

Wafer Fab Site:	DM5	Metallization:	Al0.5%Cu
Wafer Fab Process:	50HPA07	# Pins-Designator, Family:	10-DGS, MSOP
Assembly Site:	NS2		

**Qualification:**  Plan  Test Results

Reliability Test	Conditions	Sample Size/Fail
Electrical Characterization	Full Temperature	Pass
ESD - CDM	250 V/1-3	3/0

<b>Qual Vehicle: DAC8562SDSCR</b>			
<b>Die Construction Details</b>			
Wafer Fab Site:	DM5	Metallization:	Al0.5%Cu
Wafer Fab Process:	50HPA07	# Pins-Designator, Family:	10-DSC, SON
Assembly Site:	MLA		
<b>Qualification:</b> <input type="checkbox"/> <b>Plan</b> <input checked="" type="checkbox"/> <b>Test Results</b>			
<b>Reliability Test</b>		<b>Conditions</b>	<b>Sample Size/Fail</b>
Electrical Characterization		Full Temperature	Pass
ESD - HBM		1000 V/4-6	3/0
ESD - CDM		250 V/16-18	3/0
Latch-up		QSS009-004/-	6/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>